

# **HAT2129H**

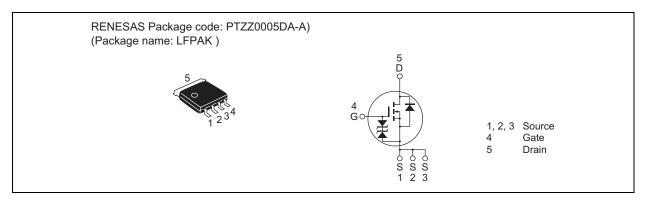
# Silicon N Channel Power MOS FET Power Switching

REJ03G0049-0500 Rev.5.00 Sep 20, 2005

#### **Features**

- Capable of 7 V gate drive
- Low drive current
- High density mounting
- Low on-resistance  $R_{DS(on)}\!=6~m\Omega~typ.~(at~V_{GS}=10~V) \label{eq:RDS(on)}$

#### **Outline**



#### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	40	V
Gate to source voltage	V <sub>GSS</sub>	±20	V
Drain current	I <sub>D</sub>	30	A
Drain peak current	I <sub>D(pulse)</sub> Note1	120	A
Body-drain diode reverse drain current	I <sub>DR</sub>	30	Α
Avalanche current	I <sub>AP</sub> Note 3	20	Α
Avalanche energy	E <sub>AR</sub> Note 3	32	mJ
Channel dissipation	Pch Note2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1.  $PW \le 10 \mu s$ , duty cycle  $\le 1\%$ 

2. Tc = 25°C

3. Value at Tch = 25°C, Rg  $\geq$  50  $\Omega$ 

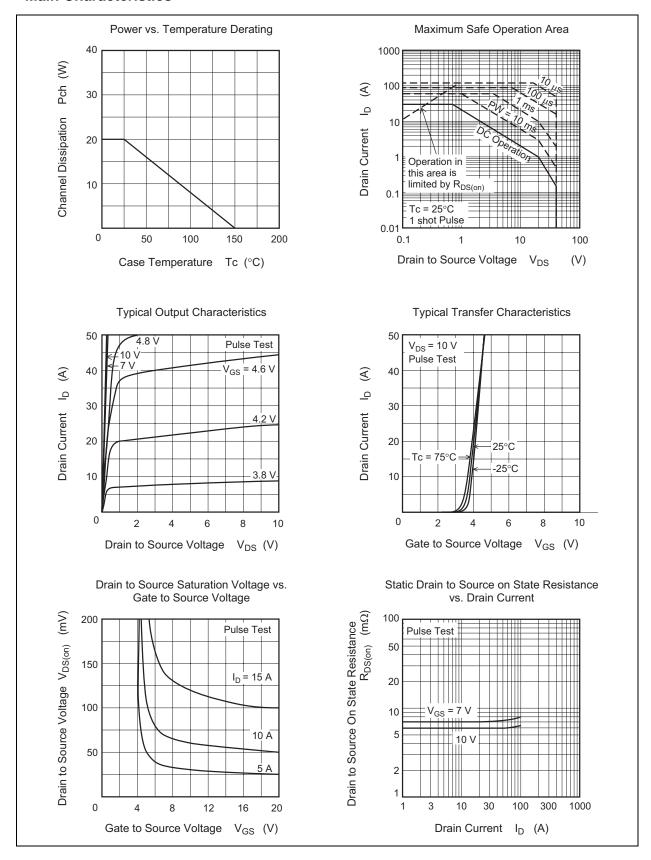
## **Electrical Characteristics**

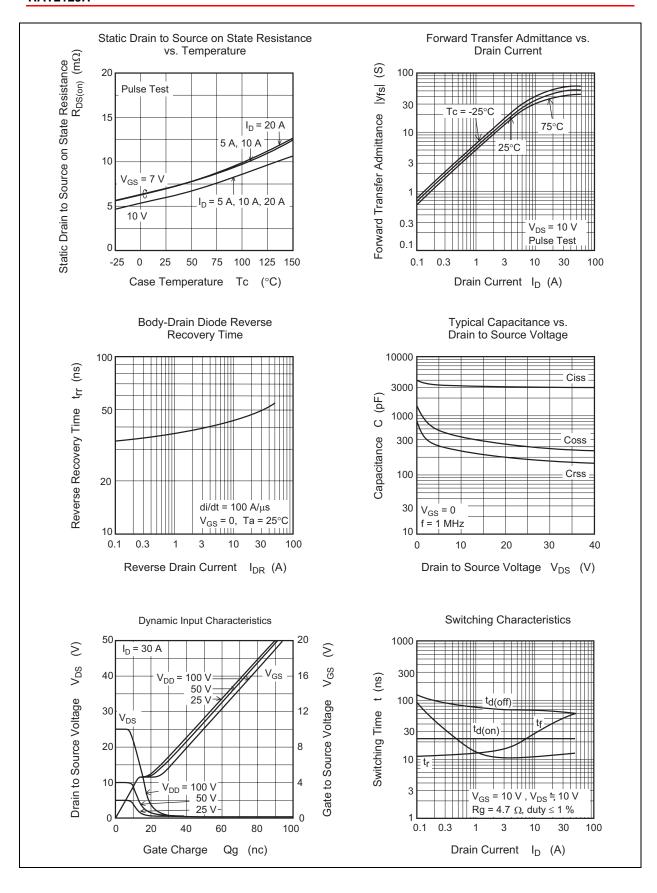
 $(Ta = 25^{\circ}C)$ 

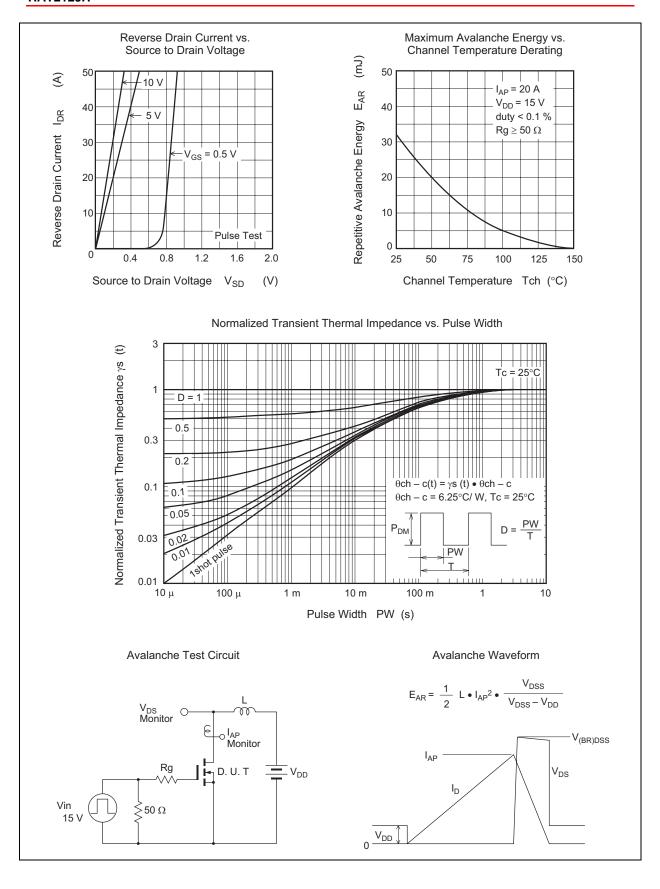
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	40	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>	_	_	±10	μΑ	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	1	μΑ	$V_{DS} = 40 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	_	3.5	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Static drain to source on state	R <sub>DS(on)</sub>	_	6.0	7.5	mΩ	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note4}}$
resistance	R <sub>DS(on)</sub>	_	7.0	9.5	mΩ	$I_D = 15 \text{ A}, V_{GS} = 7 \text{ V}^{\text{Note4}}$
Forward transfer admittance	y <sub>fs</sub>	24	40	_	S	I <sub>D</sub> = 15 A, V <sub>DS</sub> = 10 V Note4
Input capacitance	Ciss	_	3200	_	pF	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz
Output capacitance	Coss	_	450	_	pF	]
Reverse transfer capacitance	Crss	_	260	_	pF	
Total gate charge	Qg	_	46	_	nC	$V_{DD} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$
Gate to source charge	Qgs	_	13.5	_	nC	
Gate to drain charge	Qgd	_	7.5	_	nC	
Turn-on delay time	t <sub>d(on)</sub>	_	22	_	ns	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A},$
Rise time	t <sub>r</sub>	_	33	_	ns	$V_{DD}\cong 10~V,~R_L=0.67~\Omega,$
Turn-off delay time	$t_{d(off)}$	_	67	_	ns	$Rg = 4.7 \Omega$
Fall time	t <sub>f</sub>	_	11	_	ns	]
Body-drain diode forward voltage	$V_{DF}$	_	0.84	1.10	V	IF = 30 A, V <sub>GS</sub> = 0 Note4
Body-drain diode reverse	t <sub>rr</sub>	_	50	_	ns	IF = 30 A, V <sub>GS</sub> = 0
recovery time						$di_F/dt = 50 A/ \mu s$

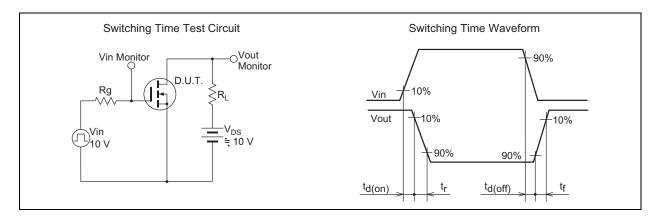
Notes: 4. Pulse test

#### **Main Characteristics**

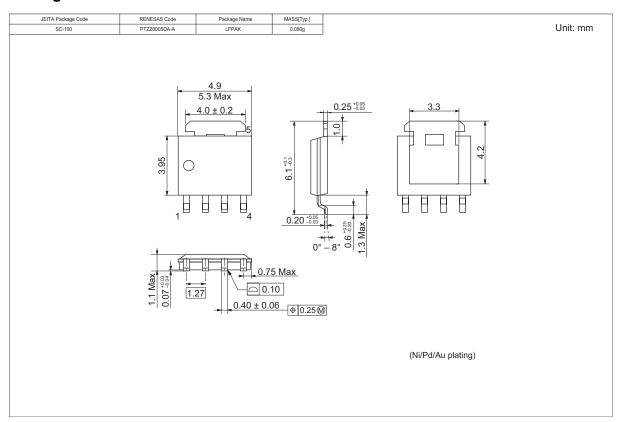








## **Package Dimensions**



# **Ordering Information**

Part Name	Quantity	Shipping Container
HAT2129H-EL-E	2500 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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